SAMSUNG ELECTRO-MECHANICS

SPECIFICATION

- **Supplier : Samsung electro-mechanics**
- **Product : Multi-layer Ceramic Capacitor**
- **Samsung P/N : CL10B821JB8NNNC**
- **Description : CAP, 820pF, 50V, ±5%, X7R, 0603**

A. Samsung Part Number

CL	10	B	821	J	B	8	N	N	N	C
①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩	⑪

① **Series**	Samsung Multi-layer Ceramic Capacitor		
② **Size**	0603 (inch code)	L: 1.6 ±0.1 mm	W: 0.8 ±0.1 mm
③ **Dielectric**	X7R	⑧ **Inner electrode**	Ni
④ **Capacitance**	820 pF	**Termination**	Cu
⑤ **Capacitance tolerance**	±5 %	**Plating**	Sn 100% (Pb Free)
		⑨ **Product**	Normal
⑥ **Rated Voltage**	50 V	⑩ **Special**	Reserved for future use
⑦ **Thickness**	0.8 ±0.1 mm	⑪ **Packaging**	Cardboard Type, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1㎑±10% 1.0±0.2Vrms
Tan δ (DF)	0.025 max.	
Insulation Resistance	10,000Mohm or 500Mohm·uF Whichever is Smaller	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characterisitcs	X7R (From -55℃ to 125℃, Capacitance change shoud be within ±15%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g·F, for 10±1 sec.
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 95% of terminal surface is to be soldered newly	1) Sn63Pb37 solder 235±5℃, 5±0.5sec. 2) SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±7.5% Tan δ, IR : initial spec.	Solder pot : 270±5℃, 10±1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within ±5% Tan δ, IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)
Humidity	Capacitance change : within ±12.5% Tan δ : 0.05 max IR : 1000Mohm or 50Mohm · uF Whichever is Smaller	40±2℃, 90~95%RH, 500+12/-0hrs
Moisture Resistance	Capacitance change : within ±12.5% Tan δ : 0.05 max IR : 500Mohm or 25Mohm · uF Whichever is Smaller	With rated voltage 40±2℃, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within ±12.5% Tan δ : 0.05 max IR : 1000Mohm or 50Mohm · uF Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within ±7.5% Tan δ, IR : initial spec.	1 cycle condition Min. operating temperatur → 25℃ → Max. operating temperature → 25℃ 5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 250±5℃, 6sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.